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**POLYPROPYLENE RESIN COMPOSITION**

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**Abstract**

**PROBLEM TO BE SOLVED:** To obtain a polypropylene resin composition from which chlorine and alkali metal components are not extracted even by extracting the formed material by water, and capable of being suitably used for a package of an electronic part or an electronic material extremely prohibited from a halogen compound or an alkali metal compound such as a silicon wafer.

**SOLUTION:** This polypropylene resin composition is obtained by adding 10-10000ppm an alkaline earth metal salt of a higher aliphatic carboxylic acid to a polypropylene resin containing  $\leq 5$ ppm chlorine content and consisting of a propylene homopolymer having  $\geq 0.930$  mesopentad ratio or a block copolymer of propylene having a homopolymer part of propylene having  $\geq 0.930$  mesopentad ratio with ethylene.

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